



Title of Change:	Qualification of Sub-contractor Thailand for the Assembly Material change.							
Proposed First Ship date:	2 April 2019							
Contact Information:	Contact your local ON Semiconductor Sales Office or < wirasa.nontharith@onsemi.com >							
Samples:	Contact your local ON Semiconductor Sales Office or < PCN.Samples@onsemi.com > Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.							
Type of Notification:	<p>This is an Initial Product/Process Change Notification (IPCEN) sent to customers. IPCENs are typically issued 30 days prior to the issuance of the Final Change Notice (FCEN). An IPCEN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.</p> <p>The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FCEN). This IPCEN notification will be followed by a Final Product/Process Change Notification (FCEN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com></p>							
Change Part Identification:	Date code will identify unit with this change.							
Change Category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____							
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Site Transfer <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Other: _____							
Sites Affected:	ON Semiconductor Sites: NONE	External Foundry/Subcon Sites: Sub-con Thailand						
Description and Purpose:								
ON Semiconductor would like to inform its customers of the qualification of Sub-con Thailand for the assembly changing the Die Attach Material from Epoxy Dispense (QMI519) to CDAF215. This is to improve the epoxy fillet height to meet customer requirement and also improve DA quality at assembly process (no epoxy overflow, bridging, fillet height out, epoxy on die, epoxy on lead, epoxy void).								
<table border="1" style="width: 100%; text-align: center;"> <thead> <tr style="background-color: #92d050;"> <th></th> <th>Before Change Description</th> <th>After Change Description</th> </tr> </thead> <tbody> <tr> <td>Die Attach</td> <td>Epoxy Dispense (QMI519)</td> <td>CDAF215</td> </tr> </tbody> </table>				Before Change Description	After Change Description	Die Attach	Epoxy Dispense (QMI519)	CDAF215
	Before Change Description	After Change Description						
Die Attach	Epoxy Dispense (QMI519)	CDAF215						
There is no product marking change as a result of this change.								



Qualification Plan:

QV DEVICE NAME: 74LVTH125MX

RMS: O42578

PACKAGE: F456 | SOIC14

Test	Specification	Condition	Interval
HTOL	JESD22-A108	Ta=145°C, 100 % max rated Vcc	504 hrs
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C	
HAST-PC	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs

List of Affected Parts:

Part Number	Qualification Vehicle
74LVTH125MX	74LVTH125MX (QV1 Big die size) MM74HC08MX (QV2 Small die size)
MM74HC164MX	
74LCX00MX	
74LCX08MX	
74LCX125MX	
74LCX07MX	
74ACT04SCX	
74VHC04MX	
74VHC14MX	
MM74HC125MX	
MM74HC02MX	
74VHC00MX	
MM74HC08MX	
MM74HC32MX	
74VHCT08AMX	



Appendix A: Changed Products

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Product	Customer Part Number	Qualification Vehicle
74ACT04SCX		74LVTH125MX, MM74HC08MX
74LCX00MX		74LVTH125MX, MM74HC08MX
74LCX07MX		74LVTH125MX, MM74HC08MX
74LCX08MX		74LVTH125MX, MM74HC08MX
74LCX125MX		74LVTH125MX, MM74HC08MX
74LVTH125MX		74LVTH125MX, MM74HC08MX
74VHC00MX		74LVTH125MX, MM74HC08MX
74VHC04MX		74LVTH125MX, MM74HC08MX
74VHC14MX		74LVTH125MX, MM74HC08MX
74VHCT08AMX		74LVTH125MX, MM74HC08MX
MM74HC02MX		74LVTH125MX, MM74HC08MX
MM74HC08MX		74LVTH125MX, MM74HC08MX
MM74HC125MX		74LVTH125MX, MM74HC08MX
MM74HC164MX		74LVTH125MX, MM74HC08MX
MM74HC32MX		74LVTH125MX, MM74HC08MX